## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Application of

Applicant Title

: David L. Chapek

: METHOD FOR CONTROLLING THE MORPHOLOGY OF DEPOSITED SILICON ON A SILICON DIOXIDE SUBSTRATE

AND SEMICONDUCTOR DEVICES INCORPORATING SUCH

DEPOSITED SILICON

: MIO 0037 VA Docket No.

Assistant Commissioner for Patents

Washington, D.C. 20231

Sir:

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## PRELIMINARY AMENDMENT

Please preliminarily amend the above-identified application as follows.

IN THE TITLE

Please delete the title and insert the following new title: SEMICONDUCTOR DEVICES INCLUDING A LAYER OF POLYCRYSTALLINE SILICON HAVING A SMOOTH

MORPHOLOGY~.

## IN THE SPECIFICATION

At page 1 after the Title, please insert the following:

~CROSS REFERENCE TO RELATED APPLICATIONS

This application is a division of U.S. Patent Application Serial No. 09/072,262, filed May 4, 1998.~

## IN THE CLAIMS

Please cancel claims 1-8, and 13.

Please amend claims 9-12 and 14 to read as follows:

A semiconductor device precursor comprising:

a semiconductor substrate: a layer of silicon dioxide formed on said semiconductor substrate, said layer of silicon

dioxide having been doped with hydrogen ions deposited by a plasma source ion implantation process [to provide a layer of polycrystalline silicon, which is subsequently

deposited on said layer of silicon dioxide with a smooth morphology]; and